

POWER SEMICONDUCTOR PACKAGE WITH STRAP

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ABSTRACT

10 A semiconductor package and a method for fabricating a semiconductor package
are disclosed. In one embodiment, the semiconductor package includes an exposed
portion of a conductive strap at a package horizontal first surface and exposed surfaces of
multiple leads at a package horizontal second surface. A power semiconductor die is
mounted on a die pad connected to at least one lead having an exposed surface. Heat
generated by the die within the package may be dissipated through thermal paths
15 including the exposed surfaces.